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Digital data signal multiplexing - producing time-division multiplex optical signals by modulation with different-wavelength light beams NoAbstract Dwg 6/7
Patent Assignee: NIPPON TELEGRAPH & TELEPHONE CORP

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 63059228	A	19880315	JP 86203108	A	19860829	198816	B

Priority Applications (Number Kind Date): JP 86203108 A (19860829)

Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 63059228	A		11		

Derwent World Patents Index

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Dialog® File Number 351 Accession Number 7475692

Photocurable and flexible compsn. for solder resisting - comprises photopolymerisable prepolymer, photopolymerisable cpd. contg. bornyl acrylate and initiator
Patent Assignee: TOYOBO KK

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 61203108	A	19860909	JP 8542471	A	19850304	198642	B

Priority Applications (Number Kind Date): JP 8542471 A (19850304)

Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 61203108	A		9		

Abstract:

JP 61203108 A

Compsn. comprises (A) photopolymerisable prepolymer, (B) photopolymerisable cpd. contg. bornyl type acrylate cpd. and (C) photopolymerisation initiator.

(A) is, e.g., epoxyacrylate such as diglycidyl ether of bisphenol A, phenol novolak type polyepoxy cpd., cresol novolak type polyepoxy cpd. or (meth)acrylate cpd. of polyepoxy cpd. of polyhydric alcohol and urethane (meth)acrylate cpd. Bornyl cpd. is, e.g., bornyl (meth)acrylate, isobornyl (meth)acrylate and phenylbornyl (meth)acrylate. (B) is, e.g., methyl (meth)acrylate, 2-hydroxyethyl (meth)acrylate, polyethylene glycol mono(meth)acrylate, dimethylaminoethyl (meth)acrylate, ethylene glycol di(meth)acrylate and trimethylolpropane tri(meth)acrylate. (C) is, e.g., benzyl dimethyl ketal, benzyl dimethyl ether, benzoin ethyl ether, benzoin, 9,10-anthraquinone, benzophenone, 2-hydroxy-2-methyl propiophenone, diphenyl disulphide, or thioxanthone. (A):(B) wt. ratio is 90:10-10:90 pref. 80:20-20:80. Amt. of bornyl cpd. in (B) is 10-80 pref. 20-60wt.%. Amt. of (C) w.r.t. whole compsn. is 0.05-20 pref. 1-10wt.%.

USE/ADVANTAGE - Compsn. is useful as a solder resist ink for permanent protective films for flexible printed circuit board. The ink is cured in short time by UV-irradiation and has enhanced adhesiveness, thermal resistance, electric insulation property, solvent resistance, flame retardancy and flexibility. (9pp Dwg.No.0/0)

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Dialog® File Number 351 Accession Number 4773187

Basic Patent (Number,Kind,Date): JP 63059228 A2 880315

PATENT FAMILY:

Japan (JP)

Patent (Number,Kind,Date): JP 63059228 A2 880315

MULTIPLEX SYSTEM (English)

Patent Assignee: NIPPON TELEGRAPH & TELEPHONE

Author (Inventor): HAGISHIMA KOICHI

Priority (Number,Kind,Date): JP 86203108 A 860829

Applic (Number,Kind,Date): JP 86203108 A 860829

IPC: * H04B-009/00; H04J-003/00

Derwent WPI Acc No: ; G 88-109626

JAPIO Reference No: ; 120281E000109

Language of Document: Japanese

INPADOC/Family and Legal Status

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Dialog® File Number 345 Accession Number 8076499

Basic Patent (Number,Kind,Date): JP 61203108 A2 860909

PATENT FAMILY:

Japan (JP)

Patent (Number,Kind,Date): JP 61203108 A2 860909

PHOTOCURABLE FLEXIBLE COMPOSITION (English)

Patent Assignee: TOYO BOSEKI

Author (Inventor): NAGAHARA SHIGENORI; ABE SHUNZO; MIYAKE HIDEO

Priority (Number,Kind,Date): JP 8542471 A 850304

Applic (Number,Kind,Date): JP 8542471 A 850304

IPC: * C08F-220/10; C08F-002/48; C08F-220/18; C09D-011/10; H05K-003/28

CA Abstract No: * 106(10)068851R

Derwent WPI Acc No: * C 86-276528

Language of Document: Japanese

INPADOC/Family and Legal Status

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Dialog® File Number 345 Accession Number 5708530

MULTIPLEX SYSTEM

Publication Number: 63-059228 (JP 63059228 A) , March 15, 1988

Inventors:

- HAGISHIMA KOICHI

Applicants

- NIPPON TELEGR & TELEPH CORP (A Japanese Company or Corporation), JP (Japan)

Application Number: 61-203108 (JP 86203108) , August 29, 1986

International Class (IPC Edition 4):

- H04B-009/00
- H04J-003/00

JAPIO Class:

- 44.2 (COMMUNICATION--- Transmission Systems)

JAPIO Keywords:

- R002 (LASERS)
- R012 (OPTICAL FIBERS)

Abstract:

PURPOSE: To decrease the transfer time of a data signal per channel by sending a data signal in parallel by wavelength multiplex.

CONSTITUTION: Digital data signals IN(sub 1)-IN(sub s) are converted into parallel data signals P(sub 11)-P(sub 1n) and P(sub s1)-P(sub sn) by serial/parallel conversion circuits 11-1n, 1st bits P(sub 11)-P(sub s1) are subjected to time division multiplex by a multiplexer 21, a time division multiplex signal M

(sub 1) is outputted and n-th bits $P(\text{sub } 1n)$ - $P(\text{sub } sn)$ are subjected to time division multiplex by a multiplexer 2n and a time division multiplex signal $M(\text{sub } n)$ is outputted. The time division multiplex signals $M(\text{sub } 1)$ - $M(\text{sub } n)$ are modulated into optical signals of different wavelengths $\lambda(\text{sub } 1)$ - $\lambda(\text{sub } n)$ by lasers 31-3n, and subjected to wavelength multiplex by a multiplexer 40 to output a time division multiplex optical signal OUT. (From: *Patent Abstracts of Japan*, Section: E, Section No. 641, Vol. 12, No. 281, Pg. 109, August 02, 1988)

JAPIO

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Dialog® File Number 347 Accession Number 2442328

PHOTOCURABLE FLEXIBLE COMPOSITION

Publication Number: 61-203108 (JP 61203108 A) , September 09, 1986

Inventors:

- NAGAHARA SHIGENORI
- ABE SHUNZO
- MIYAKE HIDEO

Applicants

- TOYOBO CO LTD (A Japanese Company or Corporation), JP (Japan)

Application Number: 60-042471 (JP 8542471) , March 04, 1985

International Class (IPC Edition 4):

- C08F-220/10
- C08F-002/48
- C08F-220/18
- C09D-011/10
- H05K-003/28

JAPIO Class:

- 14.2 (ORGANIC CHEMISTRY--- High Polymer Molecular Compounds)
- 29.4 (PRECISION INSTRUMENTS--- Business Machines)
- 42.1 (ELECTRONICS--- Electronic Components)

JAPIO Keywords:

- R044 (CHEMISTRY--- Photosensitive Resins)

Abstract:

PURPOSE: The titled composition excellent in adhesion, soldering heat resistance, flame retardancy and electrical properties and useful for permanent protective films for flexible printed wiring boards.

prepared by mixing a photocurable prepolymer with a specified photopolymerizable compound and a photoinitiator.

CONSTITUTION: To a mixture of 90-10wt% photopolymerizable prepolymer (e.g., bisphenol A epoxy acrylate) and 10-90wt% photopolymerizable compound having at least one photopolymerizable double bond (e.g., 2-hydroxyethyl methacrylate) containing 10-80wt% bornyl acrylate compound (e.g., isobornyl methacrylate), 0.05-20wt% photoinitiator (e.g., 2-ethylanthraquinone) and, optionally, 10-60wt% extender pigment (e.g., talc), an inorganic filler, a thixotropic agent, a levelling agent, a defoamer, etc., are added, and the obtained mixture is kneaded. (From: *Patent Abstracts of Japan*, Section: C, Section No. 400, Vol. 11, No. 30, Pg. 159, January 29, 1987)

JAPIO

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Dialog® File Number 347 Accession Number 1989008